

# Molding Type Module IGBT, 1-in-1 Package, 1200 V and 400 A



	\-PAK

PRODUCT SUMMARY					
V <sub>CES</sub>	1200 V				
I <sub>C</sub> at T <sub>C</sub> = 80 °C	400 A				
$V_{CE(on)}$ (typical) at $I_C = 400 \text{ A}, 25 \text{ °C}$	3.10 V				
Speed	8 kHz to 30 kHz				
Package	Double INT-A-PAK				
Circuit	Single switch with AP diode				

#### **FEATURES**

- 10 µs short circuit capability
- · Low switching losses
- Rugged with ultrafast performance
- V<sub>CE(on)</sub> with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### **TYPICAL APPLICATIONS**

- Switching mode power supplies
- · Inductive heating
- · Electronic welder

#### **DESCRIPTION**

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welder and inductive heating.

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V <sub>CES</sub>		1200	٧	
Gate to emitter voltage	$V_{GES}$		± 20	V	
Collector ourrent at T. = 150 °C	l-	T <sub>C</sub> = 25 °C	550		
Collector current at T <sub>J</sub> = 150 °C	I <sub>C</sub>	T <sub>C</sub> = 80 °C	400		
Pulsed collector current	I <sub>CM</sub> <sup>(1)</sup>	T <sub>C</sub> = 80 °C	800	Α	
Diode continuous forward current	I <sub>F</sub>		400		
Diode maximum forward current	I <sub>FM</sub>		800		
Maximum power dissipation	P <sub>D</sub>	T <sub>J</sub> = 150 °C	2841	W	
Short circuit withstand time	t <sub>SC</sub>	T <sub>J</sub> = 125 °C	10	μs	
RMS isolation voltage	V <sub>ISOL</sub>	f = 50 Hz, t = 1 min	2500	V	

#### Note

<sup>(1)</sup> Repetitive rating: pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS (T <sub>C</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V <sub>(BR)CES</sub>	T <sub>J</sub> = 25 °C	1200	-	-	
Collector to emitter voltage	V <sub>CE(on)</sub>	$V_{GE} = 15 \text{ V}, I_{C} = 400 \text{ A}, T_{J} = 25 ^{\circ}\text{C}$	-	3.10	3.60	V
Collector to entitler voltage		V <sub>GE</sub> = 15 V, I <sub>C</sub> = 400 A, T <sub>J</sub> = 125 °C	-	3.45	-	
Gate to emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$ , $I_{C} = 4$ mA, $T_{J} = 25$ °C	4.4	4.90	3.60	
Collector cut-off current	I <sub>CES</sub>	$V_{CE} = V_{CES}$ , $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA
Gate to emitter leakage current	I <sub>GES</sub>	$V_{GE} = V_{GES}$ , $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t <sub>d(on)</sub>		-	680	-	ns mJ
Rise time	t <sub>r</sub>	7	-	142	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 400 \text{ A}, R_{q} = 2.2 \Omega,$	-	638	-	
Fall time	t <sub>f</sub>	V <sub>GE</sub> = ± 15 V, T <sub>J</sub> = 25 °C	-	99	-	
Turn-on switching loss	E <sub>on</sub>	7	-	19.0	-	
Turn-off switching loss	E <sub>off</sub>		-	32.5	-	
Turn-on delay time	t <sub>d(on)</sub>		-	690	-	- ns
Rise time	t <sub>r</sub>		-	146	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 400 \text{ A}, R_{q} = 2.2 \Omega,$	-	669	-	
Fall time	t <sub>f</sub>	V <sub>GE</sub> = ± 15 V, T <sub>J</sub> = 125 °C	-	108	-	
Turn-on switching loss	E <sub>on</sub>		-	26.1	-	1
Turn-off switching loss	E <sub>off</sub>		-	36.7	-	mJ
Input capacitance	C <sub>ies</sub>		-	33.7	-	
Output capacitance	C <sub>oes</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 30 V, f = 1.0 MHz	-	2.99	-	nF
Reverse transfer capacitance	C <sub>res</sub>		-	1.21	-	
SC data	I <sub>SC</sub>	$t_p \leq 10~\mu s,~V_{GE} = 15~V,~T_J = 25~^{\circ}C,\\ V_{CC} = 600~V,~V_{CEM} \leq 1200~V$	-	2600	-	Α
Internal gate resistance	Rg		-	0.5	-	Ω
Stray inductance	L <sub>CE</sub>		-	-	18	nΗ
Module lead resistance, terminal to chip	R <sub>CC'+EE'</sub>	T <sub>C</sub> = 25 °C	-	0.32	-	mΩ

<b>DIODE ELECTRICAL SPECIFICATIONS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode forward voltage	V <sub>F</sub>	I <sub>F</sub> = 400 A	$T_J = 25  ^{\circ}C$	ı	1.95	2.35	V
blode forward voltage			T <sub>J</sub> = 125 °C	ı	1.85	ı	
Diede reverse receven cherge	Q <sub>rr</sub>	$I_F = 400 \text{ A}, V_R = 600 \text{ V},$ $dI_F/dt = -2850 \text{ A/}\mu\text{s},$ $V_{GE} = -15 \text{ V}$	$T_J = 25  ^{\circ}C$	-	24.1	-	μС
Diode reverse recovery charge			T <sub>J</sub> = 125 °C	-	44.3	-	
Diede peek vereen vereen en vere	I <sub>rr</sub>		T <sub>J</sub> = 25 °C	-	220	-	Α
Diode peak reverse recovery current			T <sub>J</sub> = 125 °C	-	295	-	] ^
Die de verreur vereuren, en ever	E <sub>rec</sub>		T <sub>J</sub> = 25 °C	-	13.9	-	mJ
Diode reverse recovery energy			T <sub>J</sub> = 125 °C	-	24.8	-	1110



THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction temperature range	e T <sub>J</sub>		-	-	150	°C	
Storage temperature range	T <sub>Stg</sub>		-40	-	125	°C	
Junction to case IGB			-	-	0.044		
per module Diod	R <sub>thJC</sub>		-	-	0.088	K/W	
Case to sink	R <sub>thCS</sub>	Conductive grease applied	-	0.035	-		
Mounting toyour		Power terminal screw: M5	2.5 to 5.0		)	Nan	
Mounting torque		Mounting screw: M6	3.0 to 6.0		Nm		
Weight				300		g	

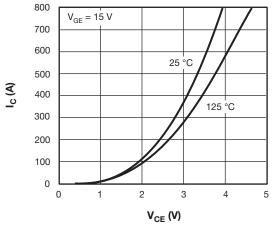


Fig. 1 - IGBT Typical Output Characteristics

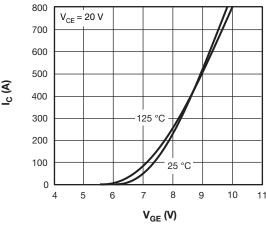


Fig. 2 - IGBT Typical Transfer Characteristics

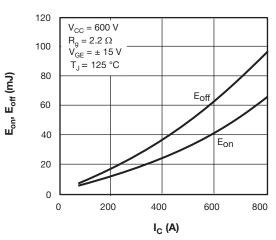


Fig. 3 - IGBT Switching Loss vs. Collector Current

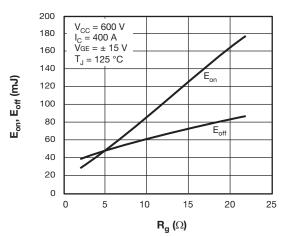


Fig. 4 - IGBT Switching Loss vs. Gate Resistor

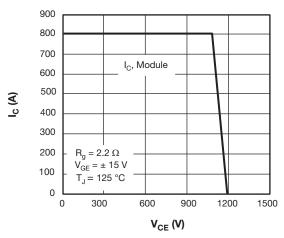


Fig. 5 - RBSOA

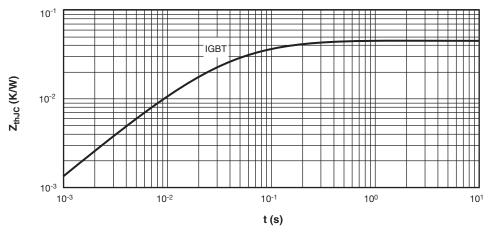


Fig. 6 - IGBT Transient Thermal Impedance

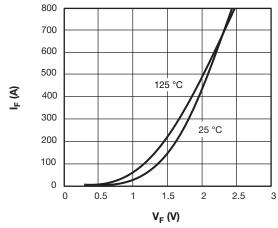


Fig. 7 - Diode Typical Forward Characteristics

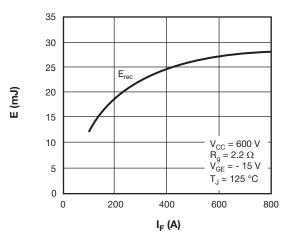


Fig. 8 - Diode Switching Loss vs. IF

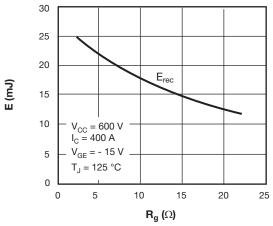


Fig. 9 - Diode Switching Loss vs.Rg

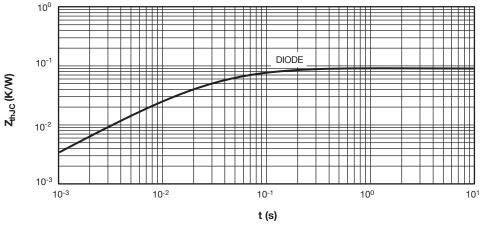
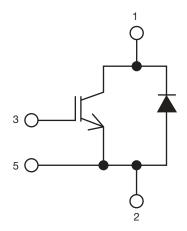


Fig. 10 - Diode Transient Thermal Impedance

### **CIRCUIT CONFIGURATION**



LINKS TO REI	ATED DOCUMENTS
Dimensions	www.vishay.com/doc?95526



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